



PRODUCT DATASHEET



- PTH Lamp
- 3mm Cylindrical 3.8t
- Red (625nm)

NOR16L89R (Bulk) NOR16L89RT (Taping)



<u>3mm Cylindrical Lamp</u>



Compliant

FEATURES:

- Package: PTH Lamp 3mm Cylindrical 3.8t
- Forward Current: 20mA
- Forward Voltage (typ.): 2.0V
- Luminous Intensity (typ.): 200mcd @20mA
- Colour: Red
- Wavelength: 625nm
- Viewing angle: 150°
- Materials:
 - Die: AlInGaP
 - Resin: Epoxy (Water Clear)
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- Grouping parameters:
 - Forward voltage
 - Luminous intensity
 - Wavelength
- Soldering methods: Hand; Wave Soldering (DIP)
- Preconditioning: acc. to JEDEC Level 3
- Packing: 500pcs/Bulk; 2000pcs/Taping

3mm Cylindrical Lamp

APPLICATIONS:

- Indicator
- Switch

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Signal Light



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/10@1KHz	I _{FP}	100	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	85	mW
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{stg}	-40~+100	°C

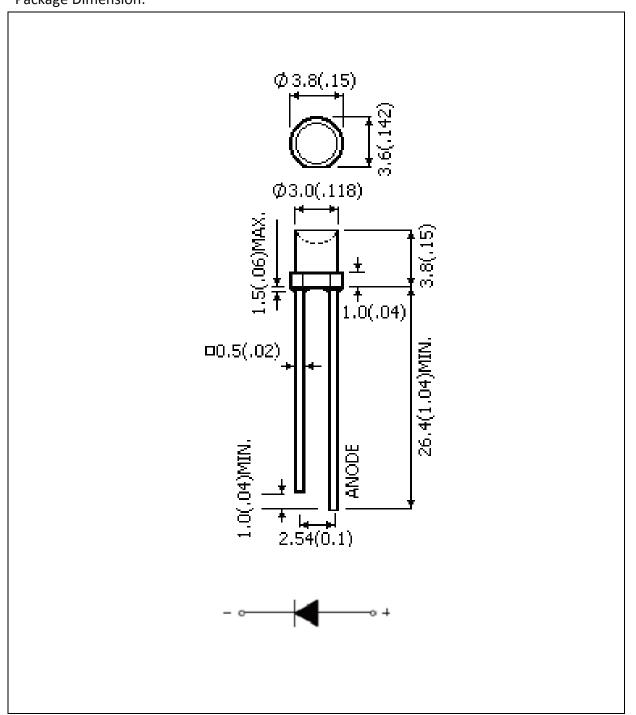
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Sumbol	Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V _F	1.8	2.0	2.5	V	I _F =20mA
Luminous Intensity	Iv	170	200	265	mcd	I _F =20mA
Dominant Wavelength	λ_{D}	620	625	630	nm	I _F =20mA
Peak Wavelength	λ_{P}		635		nm	I _F =20mA
Spectral Line H-Width	Δλ		22		nm	I _F =20mA
Viewing Angle	20 _{1/2}		150		deg	I _F =20mA

1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V

OUTLINE DIMENSION:





1. All dimensions are in millimetre (mm).

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2. Tolerance ± 0.25 mm, unless otherwise noted.

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BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
V18	1.8	2.5	V

Luminous Intensity Classifications (I_F = 20mA):

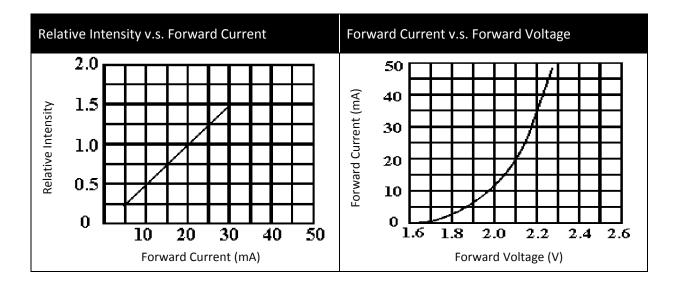
Code	Min.	Max.	Unit
L1	170	265	mcd

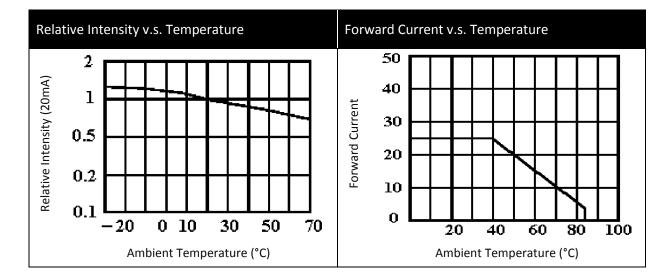
Wavelength Classifications ($I_F = 20mA$):

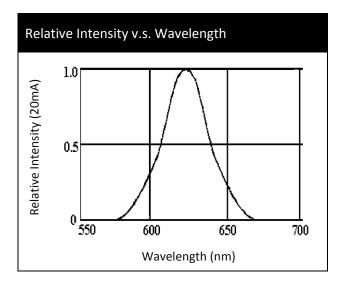
Code	Min.	Max.	Unit
R620	620	625	2.22
R625	625	630	nm



ELECTRO-OPTICAL CHARACTERISTICS:







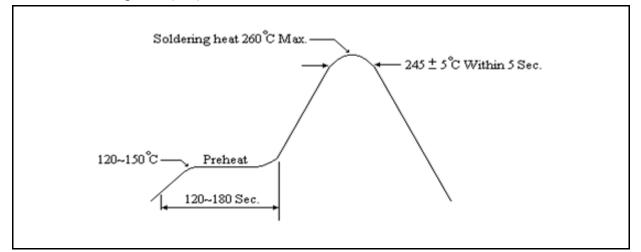


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 300°C Max. (25W Max.).
- Soldering Time: 3 seconds ± 1 sec.
- Maximum reflow soldering: 1 time.

Wave / Soldering Heat (DIP):



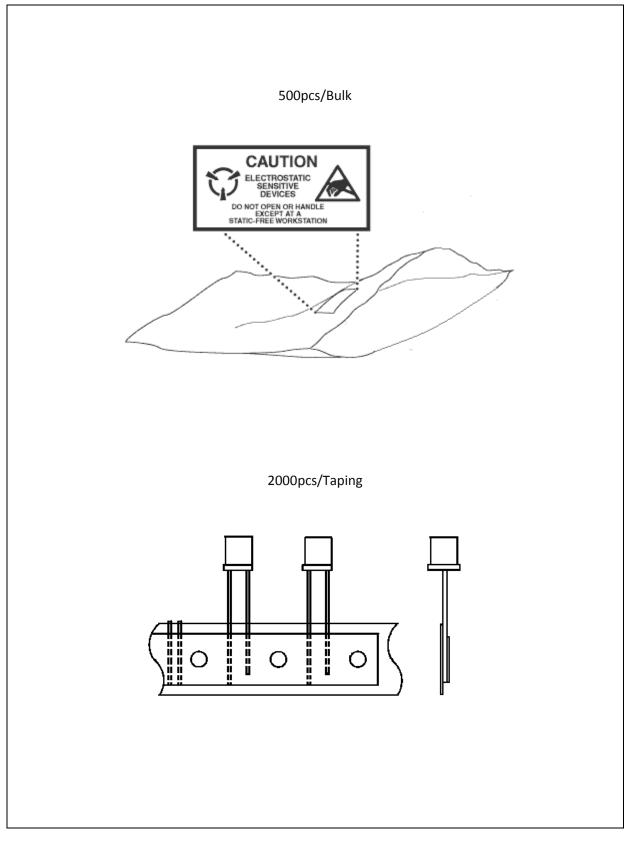
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

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REVISION RECORD:

Version	Date	Summary of Revision
A1.0	04/08/2015	Datasheet set-up.
A1.1	21/09/2015	Update solder profile.

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